Electronic Patent Application Fee Transmittal							
Application Number:	10550153						
Filing Date:	20-Sep-2005						
Title of Invention:	Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product						
First Named Inventor/Applicant Name:	Toshikazu Okubo						
Filer:	Song Zhu						
Attorney Docket Number:	38915.00045						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Petition fee- 37 CFR 1.17(f) (Group I)		1462	1	400	400		
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			400